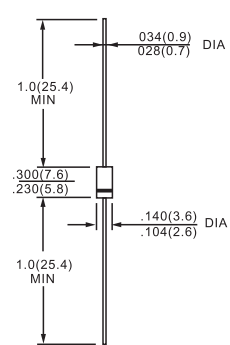




FEATURES

- VERY LOW CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD AND REVERSE RECOVERY TIMES
- THE SPECIFICATIONS AND CURVES ENABLE THE DETERMINATION OF t_{rr} AND I_{RM} AT 100°C UNDER USERS CONDITIONS



DO-15

Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		200	V
I_{FRM}	Repetitive peak forward current *	$t_p = 5 \mu s$ $F = 1 KHz$	80	A
$I_{F(AV)}$	Average forward current *	$T_a = 95^\circ C$ $\delta = 0.5$	1.5	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10 ms$ sinusoidal	50	A
T_{stg}	Storage temperature range		-65 +150	°C
T_j	Maximum operating junction temperature		+ 150	°C
T_L	Maximum lead temperature for soldering during 10s at 4mm from case		230	°C

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I_R^*	Reverse leakage current	$V_R = V_{RRM}$	$T_j = 25^\circ C$			10	μA
			$T_j = 100^\circ C$			0.5	mA
V_F^{**}	Forward voltage drop	$I_F = 4.5 A$	$T_j = 25^\circ C$			1.2	V
			$T_j = 100^\circ C$		0.78	0.85	

RECOVERY CHARACTERISTICS

Symbol	Tests conditions			Min.	Typ.	Max.	Unit
t_{rr}	$I_F = 1 A$	$di_F/dt = -50 A/\mu s$	$V_R = 30 V$	$T_j = 25^\circ C$		35	ns
t_{fr}	$I_F = 1.5 A$	$di_F/dt = -50 A/\mu s$	Measured at $1.1 \times V_F$ max.	$T_j = 25^\circ C$	30		ns
V_{FP}	$I_F = 1.5 A$	$di_F/dt = -50 A/\mu s$		$T_j = 25^\circ C$	5		V
Q_{rr}	$I_F = 1.5 A$	$di_F/dt = -20 A/\mu s$	$V_R \leq 30 V$	$T_j = 25^\circ C$	10		nC



RATINGS AND CHARACTERISTIC CURVES BYW100-200

Fig. 1: Average forward power dissipation versus average forward current.

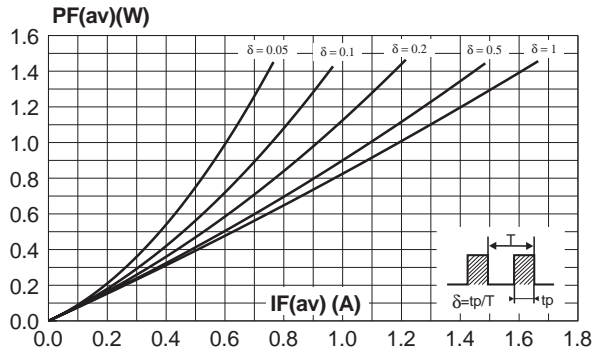


Fig. 2: Average forward current versus ambient temperature (delta=0.5).

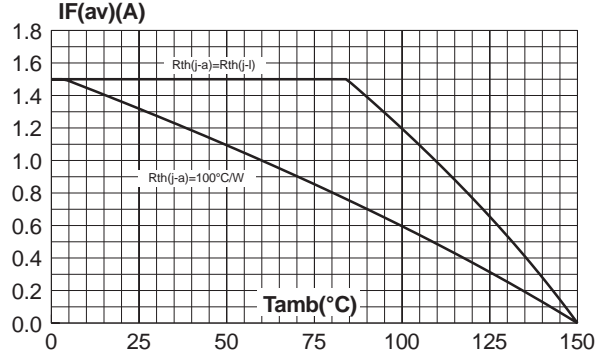


Fig. 3: Thermal resistance versus lead length.

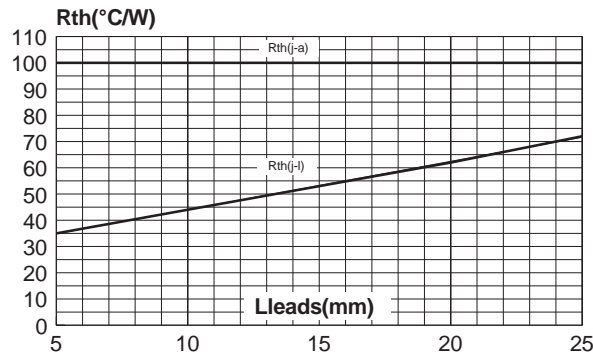


Fig. 4: Variation of thermal impedance junction to ambient versus pulse duration (recommended pad).

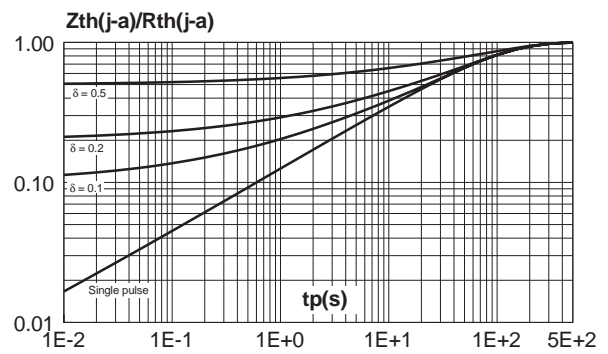


Fig. 5: Forward voltage drop versus forward current (maximum values).

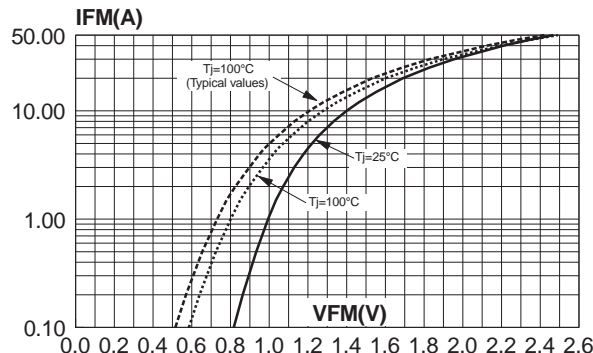


Fig. 6: Junction capacitance versus reverse voltage applied (typical values).

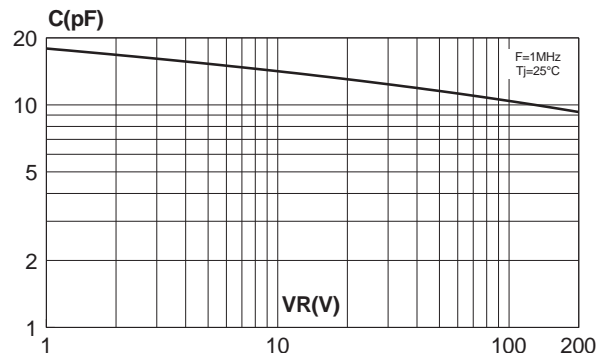


Fig. 7: Reverse recovery time versus diF/dt.

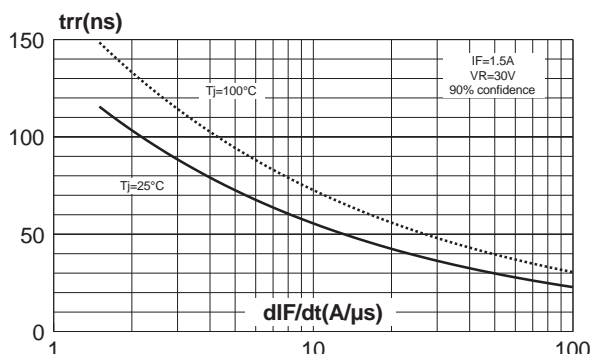


Fig. 8: Peak reverse recovery current versus diF/dt.

